



Title of Change:	Addition of ON Semiconductor Pocatello, Idaho Fab 10 as a wafer fab manufacturing location for the AMIS30623C6238RG product.
Proposed Changed Material First Ship Date:	11 September 2019
Current Material Last Order Date:	NA
Current Material Last Delivery Date:	NA
Product Category:	Active components – Integrated circuits
Contact information:	Contact your local ON Semiconductor Sales Office or Customer Quality interface.
Samples:	Contact your local ON Semiconductor Sales Office to place sample order or <PCN.samples@onsemi.com> Sample requests are to be submitted no later than 45 days after publication of this change notification.
Sample Availability Date:	24 August 2018
PPAP Availability Date:	24 August 2018
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or <Catherine.DeKeukeleire@onsemi.com>.
Type of Notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 12 months prior to implementation of the change or earlier upon customer approval. ON Semiconductor will consider this proposed change and it's conditions acceptable, unless an inquiry is made in writing within 45 days of delivery of this notice. To do so, contact PCN.Support@onsemi.com.
Change Category:	Type of Change
Process – Wafer Production	New wafer diameter New / change of metallization (specifically chip frontside)" New / change of passivation or die coating (without bare die) Change in process technology (e. g. process changes like lithography, etch, oxide deposition, diffusion, die back surface preparation/backgrind,...) Move of all or part of wafer fab to a different location/site/subcontractor (qualification of an additional manufacturing site)
Equipment	Production from a new equipment/tool which uses a different basic technology or which due to its unique form or function can be expected to influence the integrity of the final product
Process – Assembly	Change of product marking



Description and Purpose:

This Final Notification announces to customers the addition of ON Semiconductor Pocatello, Idaho Fab 10 as a wafer fab manufacturing location for the AMIS30623C6238RG product.

Material to be changed	Before Change Description	After Change Description
Wafer Fab Location	ON Semiconductor Fab2 (Oudenaarde, Belgium)	ON Semiconductor Fab2 (Oudenaarde, Belgium) or ON Semiconductor Fab10 (Pocatello, Idaho)
Wafer diameter	6 inch	8 inch
Fab process equipment	All: 6 inch equipment Photo: Canon I-Line Steppers Implant: Eaton MC Implanter Implant: AMAT HC Implanter Etch: AMAT poly etch Etch: AMAT Oxide Etch Diffusion: TEL Horizontal Furnace	All: 8 inch equipment Photo: ASM I-Line Steppers Implant: Varian MC Implanter Implant: Varian HC Implanter Etch: LAM poly etch Etch: LRC oxide etch Diffusion: BTI Vertical Furnace
Die Metallization	M1: 0.55um; M2: 0.85um	M1: 0.60um; M2: 0.90um
Die Passivation	1.1um	1.05um

	From	To
Product Marking Change		<p><i>F = Fab (2 for Fab2, T for Fab10)</i></p>

Reason / Motivation for Change:	<ul style="list-style-type: none"> - Change benefits for customer: Dual sourcing increases flexibility to handle capacity issues - Risk for late release for customer: Capacity or flexibility constraints could limit material availability 		
Anticipated impact on fit, form, function, reliability, product safety or manufacturability	<p>The Fab10 device has been qualified and validated based on the same Product Specification as the Fab2 device. The device has successfully passed the qualification tests. Potential impacts can be identified, but due to testing performed by ON Semiconductor in relation to the PCN, associated risks are verified and excluded.</p> <p>No anticipated impacts.</p>		
Sites Affected:	<table border="0" style="width: 100%;"> <tr> <td style="width: 50%;">ON Semiconductor Sites: ON Pocatello, Idaho</td> <td style="width: 50%;">External Foundry/Subcon Sites: None</td> </tr> </table>	ON Semiconductor Sites: ON Pocatello, Idaho	External Foundry/Subcon Sites: None
ON Semiconductor Sites: ON Pocatello, Idaho	External Foundry/Subcon Sites: None		



<p>Marking of Parts/ Traceability of Change:</p>	<p>For traceability the OPN of the dual source product will be updated:</p> <p>Current OPN: AMIS30632C6238RG Dual fab OPN: AMIS30623C6238RG-BAAA</p> <p>Part Marking : The dual fab part marking enables identification of the originating fabrication facility. The fab will be identified by the first character of the date code in the bottom row of text of the package marking. The character "F" will be replaced by "2" to indicate Fab 2, or it will be replaced by a "T" to indicate Fab 10. See marking diagrams above for details.</p>	
<p>Reliability Data Summary:</p> <p>NOTE: The AEC 1-pager, HTOL Aging Reports, FA Reports, and 8D Reports are attached.</p>		
<p>Electrical Characteristic Summary:</p> <p><i>To access file attachments on pdf copy of PCN, please be guided by the steps below:</i></p> <ol style="list-style-type: none"> 1. Download pdf copy of the PCN to your computer 2. Open the downloaded pdf copy of the PCN 3. Click on the paper clip icon available on the menu provided in the left/bottom portion of the screen to reveal the Attachment field 4. Then click on the attached file/s <p>NOTE: Electrical characteristics are not impacted. The Cpk Report is attached.</p>		
<p>List of Affected Parts:</p>		
<p>Current Part Number</p>	<p>New Part Number</p>	<p>Qualification Vehicle</p>
<p>AMIS30623C6238RG</p>	<p>AMIS30623C6238RG-BAAA</p>	<p>21287-001</p>



Appendix A: Changed Products

Product	Customer Part Number	New Part Number	Qualification Vehicle
AMIS30623C6238RG	0C623-008-XTP	NA	21287-900